# 507650938 12/15/2022

# PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

#### **CONVEYING PARTY DATA**

Name	Execution Date
YUNG-SHENG FANG	11/17/2022
IGOR ELKANOVICH	11/12/2022
PEI YU	11/17/2022

### **RECEIVING PARTY DATA**

Name:	GLOBAL UNICHIP CORPORATION
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State/Country:	TAIWAN
Postal Code:	30078
Name:	TAIWAN SEMICONDUCTOR MANUFACTURING COMPANY, LTD.
Street Address:	NO.8, LI-HSIN RD. 6, HSINCHU SCIENCE PARK,
City:	HSINCHU
State/Country:	TAIWAN
Postal Code:	300-78

#### **PROPERTY NUMBERS Total: 1**

Property Type	Number
Application Number:	18079001

#### CORRESPONDENCE DATA

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Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.

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ATTORNEY DOCKET NUMBER:	127271-US-PA
NAME OF SUBMITTER:	BELINDA LEE
SIGNATURE:	/Belinda Lee/

PATENT 507650938 REEL: 062111 FRAME: 0622

DATE SIGNED:	12/15/2022
Total Attachments: 4	
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PATENT REEL: 062111 FRAME: 0623

# DECLARATION AND ASSIGNMENT

# FOR UTILITY OR DESIGN PATENT APPLICATION

$\boxtimes$	Declaration Submitted With Initial Filing
OR	
	Declaration Submitted After Initial Filing (surcharge 37 CFR 1.16(f) required)
	(Title of the Invention)
	DBI ENCODING DEVICE AND DBI ENCODING METHOD
As a	a below named inventor (hereinafter designated as the undersigned), I hereby
decl	are that:
This	declaration is directed to:
$\boxtimes$	The attached application,
OR	
	United States Application Number or PCT International application number
	Filed on

The above-identified application was made or authorized to be made by me.

I believe I am the original inventor or an original joint inventor of a claimed invention in the application.

The undersigned hereby acknowledge that any willful false statement made in this declaration is punishable under 18 U.S.C. 1001 by fine or imprisonment of not more than five (5) years, or both.

#### **DECLARATION AND ASSIGNMENT**

#### FOR UTILITY OR DESIGN PATENT APPLICATION

WHEREAS, the undersigned has invented certain new and useful improvements described in the application identified.

WHEREAS, 1. Global Unichip Corporation

of

No.10, Lixing 6th Rd., Science-Based Industrial Park, Hsinchu 30078, Taiwan (R.O.C.)

2. Taiwan Semiconductor Manufacturing Company, Ltd. of No.8, Li-Hsin Rd. 6, Hsinchu Science Park, Hsinchu, Taiwan 300-78. R.O.C.

hereinafter referred to as ASSIGNEE, is desirous of acquiring the undersigned's interest in the said invention and application and in any U.S. Letters Patent which may be granted on the same:

NOW, THEREFORE, TO ALL WHOM IT MAY CONCERN: Be it known that, for good and valuable consideration, receipt of which is hereby acknowledged by the undersigned, the undersigned has/have sold, assigned and transferred, and by these presents does/do sell, assign and transfer unto the said Assignee, and Assignee's successors and assigns, all his/her/their rights, title and interest in and to the said invention and application and all future improvements thereon, and in and to any Letters Patent which may hereafter be granted on the same in the United States, the said rights, title and interest to be held and enjoyed by said Assignee as fully and exclusively as it would have been held and enjoyed by said the undersigned had this Assignment and transfer not been made, to the full end and term of any Letters Patent which may be granted thereon, or of any division, renewal, continuation in whole or in part, substitution, conversion, reissue, prolongation or extension thereof.

The undersigned further agrees/agree that he/she/they will, without charge to said Assignee, but at Assignee's expense, cooperate with Assignee in the prosecution of said application and/or applications, execute, verify, acknowledge and deliver all such further papers, including applications for Letters Patent and for the reissue thereof, and instruments of assignment and transfer thereof, and will perform such other acts as Assignee Lawfully may request, to obtain or maintain Letters Patent for said invention and improvement, and to vest title thereto in said Assignee, or Assignee's successors and assigns.

- 2 -

2022-021US 127271-US-PA

# DECLARATION AND ASSIGNMENT

# FOR UTILITY OR DESIGN PATENT APPLICATION

Signature: Tung-Sheng Fang Date: 20>2, 11,19
Legal Name of Sole or First Inventor: Yung-Sheng Fang
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Mailing Address: c/o No.10, Lixing 6th Rd., Science-Based Industrial Park, Hsinchu 30078, Taiwan (R.O.C.)
Signature:Date:
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Signature: Pei (N Date: 7022:11:17)
egal Name of Additional Joint Inventor, if any: Pei Yu
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Mailing Address: c/o No.10, Lixing 6th Rd., Science-Based Industrial Park, Hsinchu 30078, Taiwan (R.O.C.)

# DECLARATION AND ASSIGNMENT

# FOR UTILITY OR DESIGN PATENT APPLICATION

Signature:	Date:
Legal Name of Sole or Fire	Inventor: Yung-Sheng Fang
Residence: Hsinchu, Taiw	1
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Signature:	Date: 17/Nov/202
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Signature:	Date:
Legal Name of Additional	int Inventor, if any: Pei Yu
Residence: Hsinchu, Taiwa	١ .
Mailing Address: c/o No.10	Lixing 6th Rd., Science-Based Industrial Park, Hsinchu 30078, Taiwai

- 3 -